



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-04-11
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32WB07CCV6TR	F0M2*F1618B9	A	P1C7	2025-04-11
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	107	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	6x6	48	Flat	
Comment	Package : A0BE VFQFPN 6x6x0.9 48L PITCH 0.4 8205966			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	

QueryList : REACH-21st January 2025				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	FOM2*F1618B9		106.6302		6000000.0	1000000.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	7.409	mg	supplier	die	Silicon (Si)	7440-21-3		7.026	mg	948281	65892.32				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	2455	170.59				
				supplier	metallization	Copper (Cu)	7440-50-8		0.163	mg	21946	1524.94				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.052	mg	7060	490.57				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	307	21.33				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	153	10.63				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.041	mg	5525	383.91				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.106	mg	14273	991.77				
				Glue epoxy (QMI-519)	Precious metals	1.255	mg	supplier	Glue or tape	Silver (Ag)	7440-22-4		1.004	mg	800000	9411.97
								supplier	Glue or tape	Methylene diacrylate polymer	42594-17-2		0.206	mg	164000	1929.45
supplier	Glue or tape	Epoxy resin	68475-94-5						0.031	mg	25000	294.12				
supplier	Glue or tape	Epoxy cyclohexylethyltrimethoxysilane	3388-04-3						0.006	mg	5000	58.82				
SVHC	Glue or tape	Bis(α,α-dimethylbenzyl) peroxide	80-43-3						0.006	mg	5000	58.82				
supplier	Glue or tape	Palladium (Pd)	7440-05-3						0.001	mg	1000	11.76				
Bonding wire (CuPd)	Precious metals	0.345	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		0.341	mg	990000	3198.63				
				supplier	Bonding wire	Others	Proprietary		0.003	mg	10000	32.31				
Encapsulation (CEL 9240ZHF10W)	M-011 Other inorganic materials	46.034	mg	supplier	Molding Compound	Silica vitreous	60676-86-0		40.510	mg	880000	379910.28				
				supplier	Molding Compound	Biphenyl epoxy resin	85954-11-6		2.302	mg	50000	21585.81				
				supplier	Molding Compound	Phenolic resin	205830-20-2		1.795	mg	39000	16836.93				
				supplier	Molding Compound	Epoxy type resin A	Proprietary		0.921	mg	20000	8634.32				
				supplier	Molding Compound	Epoxy type resin B	Proprietary		0.414	mg	9000	3885.45				
				supplier	Molding Compound	Carbon black	1333-86-4		0.092	mg	2000	863.43				
Leadframe (C194)	Copper & its alloys	51.165	mg	supplier	Leadframe	Copper (Cu)	7440-50-8		50.029	mg	977801.9666	469181.43				
				supplier	Leadframe	Iron (Fe)	7439-89-6		1.083	mg	21169.16364	10157.66				
				supplier	Leadframe	Zinc (Zn)	7440-66-6		0.049	mg	961.6233428	461.42				
				supplier	Leadframe	Phosphorus (P)	7723-14-0		0.003	mg	67.24639034	32.27				
				supplier	Plating	Nickel (Ni)	7440-02-0		0.389	mg	918899.4478	3647.14				
External Plating (Ni/Pd/Au)	M-011 Other inorganic materials	0.423	mg	supplier	Plating	Palladium (Pd)	7440-05-3		0.029	mg	69332.73903	275.18				
				supplier	Plating	Gold (Au)	7440-57-5		0.005	mg	11767.81316	46.71				